

# Chemicals contained in products

## Package-type

Epson Package name; **QFP8-128PIN-E1/ Halogen free**

JEITA Package name; **P-QFP128-2828-0.80**

Terminal plating; **Lead(Pb) Free**

Weight; **5.79 [g]\*Note1**

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	57	Silicon	7440-21-3	57	999894	Base material
			Boron	7440-42-8	0.00011	2	Dopant
			Phosphorus	7723-14-0	0.00029	5	Dopant
			Aluminum	7429-90-5	0.0011	20	Metalization
			Arsenic *Note3	7440-38-2	0.00029	5	Dopant
			Fluorine *Note3	7782-41-4	0.00011	2	Dopant
			Titanium *Note3	7440-32-6	0.0011	20	Metalization
			Molybdenum *Note3	7439-98-7	0.0011	20	Metalization
			Tungsten *Note3	7440-33-7	0.0017	30	Metalization
			Cobalt *Note3	7440-48-4	0.00011	2	Metalization
	Stress buffer coat	1.1	Polyimide	-	1.1	1000000	Stress buffer coat *Note4
Package	Die Bonding material	7.9	Silver	7440-22-4	5.1	640000	Base material
			Epoxy resin	-	1.60	205000	Adhesive
			Phenol resin	-	0.63	80000	Adhesive
			Inorganic powder	-	0.38	48000	Additive
			Bismuth compound	-	0.21	27000	Ion trap
	Lead Frame Plating	48.6	Tin	7440-31-5	47.6	980000	Solder
			Bismuth	7440-69-9	0.96	20000	Solder
	Lead Frame	838.5	Copper	7440-50-8	792.4	945000	Conductor
			Silver	7440-22-4	4.2	5000	Inner lead plating
			Others *Note5	-	42	50000	Additive
	Bonding Wire	3.7	Gold	7440-57-5	3.7	1000000	Conductor
	Mold resin	4833	Epoxy resin	-	241.7	50000	Base material
			Silica	60676-86-0/-	4373.8	905000	Filler
			Carbon black	1333-86-4	24.2	5000	Coloring agent
Hardening chemical(ex:Phenol resin)			-	193.3	40000	Base material	

Regarding the information of chemical substances

\*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

\*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

\*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

\*Note4 The stress buffer coat may not be used depending on the individual model.

\*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included for the Cu type. And the carbon, silicon, and manganese are included for 42alloy type.